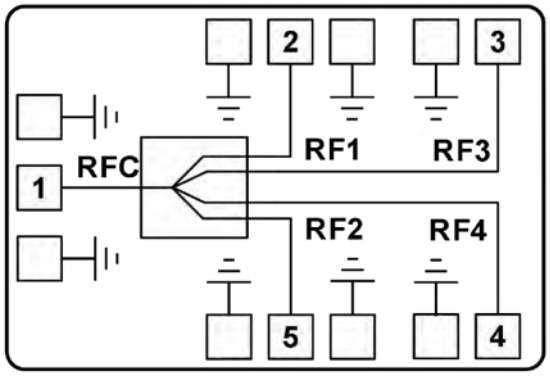
Features

- Frequency: 2-18GHz
- Insertion Loss: 2.5dB Typical
- Isolation: 18dB Typical
- Input/Output: 50Ω
- Chip Size: 3.649 x 4.724 x 0.1mm

Functional Block Diagram



Typical Applications

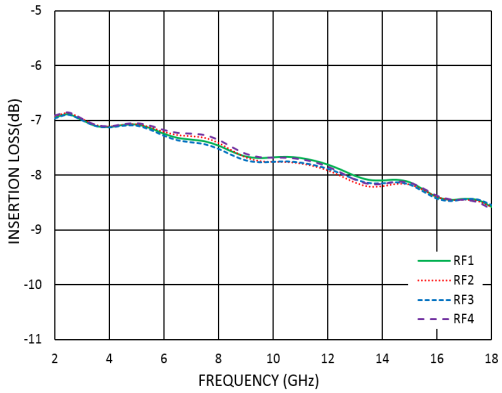
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

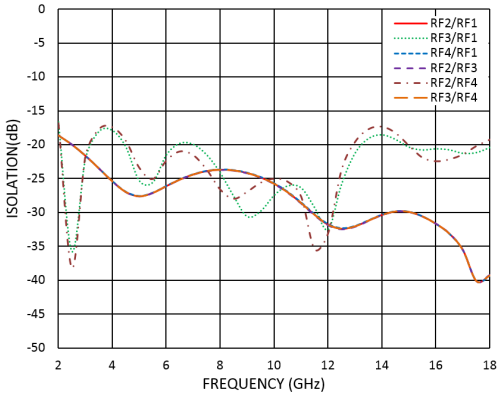
TA = +25°C ,Pin=0dBm

Parameters	Min.	Typ.	Max.	Units
Frequency	2		18	GHz
Nominal Splitter Loss		6		dB
Insertion Loss		2.5	2.6	dB
Insertion Loss Flatness		±0.75		dB
Isolation	14	18		dB
Input Return Loss	12	15		dB
Output Return Loss	16	20		dB

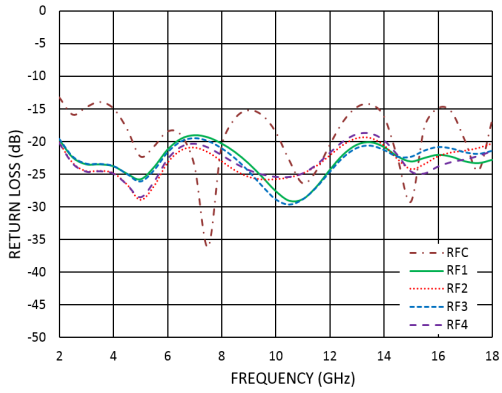
Insertion Loss vs. Frequency



Isolation vs. Frequency

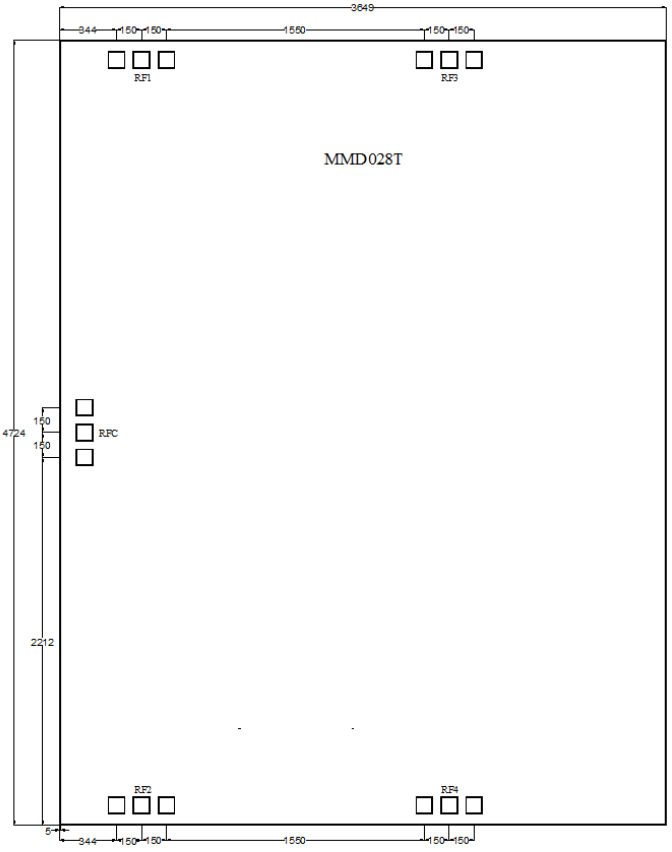


Return Loss vs. Frequency



Outline Drawing:

All Dimensions in µm



Absolute Maximum Ratings

RF Input Power	+40dBm
Operating Temperature	-55°C to +85 °C
Storage Temperature	-65°C to +150°C

No	Symbol	Description
1	RFC	RF Common Port
2,3,4,5	RF1&RF2&RF3&RF4	RF Branch Ports

Notes:

1. **Die thickness: 100µm**
2. **RF IN/OUT bond pad is 100*100µm²**
3. **Bond pad metalization: Gold**
4. **Backside metalization: Gold**
5. **Backside of the die (GND)**